



2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Wang, Kun-Chih

Serial No.: 09/880,518

Filed: 06/12/2001

For: BONDING PAD STRUCTURE

Examiner: Nguyen, Dilinh P.

Art Unit: 2814

Docket No.: JC-7265-C

TC 2800 MAIL ROOM

OCT 30 2002

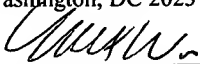
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, DC 20231 on Oct. 18, 2002.


Signature

Technology Center 2600

No fee is believed to be due in connection with this amendment and response to Office Action. If, however, any fee is believed to be due, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 500314.

RESPONSE TO OFFICE ACTION

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Sir:

The Final Office Action mailed July 29, 2002 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.